















ESD

TVS

MOS

LDO

Diode

Sensor

DC-DC

Product Specification

Domestic Part Number	IRFR24N15D
Overseas Part Number	IRFR24N15D
▶ Equivalent Part Number	IRFR24N15D





N-Ch 150V Fast Switching MOSFETs

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent Cdv/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

BVDSS	RDSON	ID
150V	88mΩ	20A

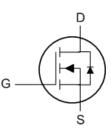
Description

The IRFR24N15D is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The IRFR24N15D meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO252 Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	150	V
V _G s	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	20	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	14	А
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	3	А
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	2.5	A
I _{DM}	Pulsed Drain Current ²	40	А
EAS	Single Pulse Avalanche Energy ³	53	mJ
I _{AS}	Avalanche Current	18	А
P _D @T _C =25°C	Total Power Dissipation ³	72.6	W
P _D @T _A =25°C	Total Power Dissipation ³	2.1	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-ambient ¹		60	°C/W
R ₀ JC	Thermal Resistance Junction-Case ¹		1.72	°C/W



N-Ch 150V Fast Switching MOSFETs

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	150			V
Danier	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =10A			88	mΩ
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =10A			100	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2		2.5	V
lass	Drain-Source Leakage Current	V _{DS} =120V , V _{GS} =0V , T _J =25°C			1	- uA
IDSS		V _{DS} =120V , V _{GS} =0V , T _J =55°C			5	
Igss	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =10A		33		S
Qg	Total Gate Charge			25.1		
Qgs	Gate-Source Charge	V _{DS} =75V , V _{GS} =4.5V , I _D =10A		6.8		nC
Q _{gd}	Gate-Drain Charge			12.6		
T _{d(on)}	Turn-On Delay Time			13		
Tr	Rise Time	V_{DD} =75V , V_{GS} =10V , R_{G} =3.3 Ω		8.2		
T _{d(off)}	Turn-Off Delay Time	I _D =10A		25		ns
T _f	Fall Time			11		
C _{iss}	Input Capacitance	V _{DS} =25V , V _{GS} =0V , f=1MHz		2285		
Coss	Output Capacitance			110		pF
Crss	Reverse Transfer Capacitance			83		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,5}	V- V- OV Force Current			20	Α
I _{SM}	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			40	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V
t _{rr}	Reverse Recovery Time	IF=10A , dI/dt=100A/μs ,		37		nS
Qrr	Reverse Recovery Charge	T _J =25°C		263		nC

Note:

- 1. The data tested by surface mounted on a 1 inch $^2\,\text{FR-4}$ board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.3mH, I_{AS} =18A
- 4.The power dissipation is limited by 150 $^{\circ}\text{C}~$ junction temperature
- 5. The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.



N-Ch 150V Fast Switching MOSFETs

Typical Characteristics

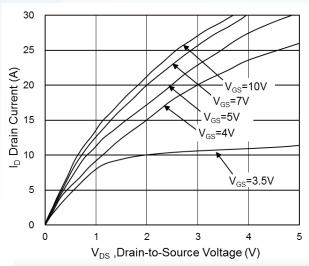


Fig.1 Typical Output Characteristics

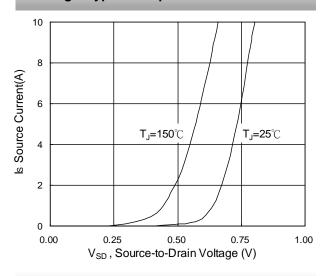


Fig.3 Forward Characteristics of Reverse

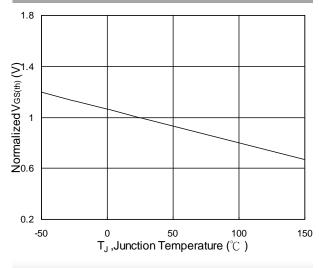


Fig.5 Normalized V_{GS(th)} vs. T_J

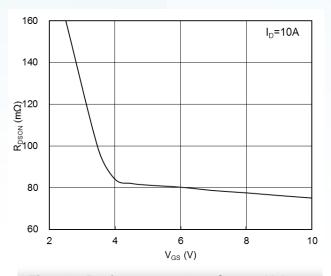


Fig.2 On-Resistance vs. Gate-Source Voltage

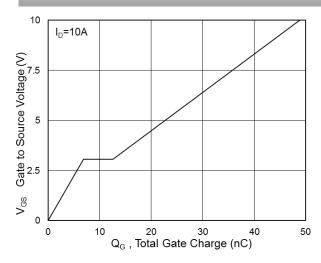


Fig.4 Gate-Charge Characteristics

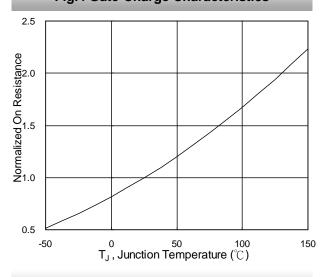


Fig.6 Normalized R_{DSON} vs. T_J



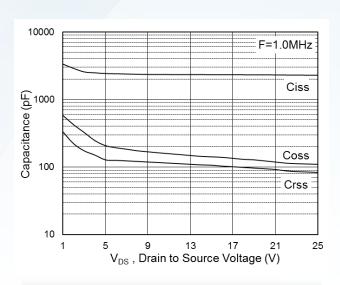


Fig.7 Capacitance

N-Ch 150V Fast Switching MOSFETs

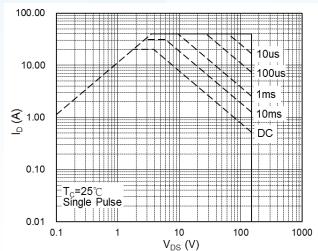


Fig.8 Safe Operating Area

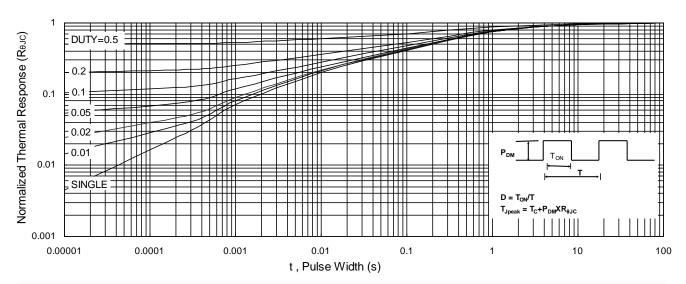


Fig.9 Normalized Maximum Transient Thermal Impedance

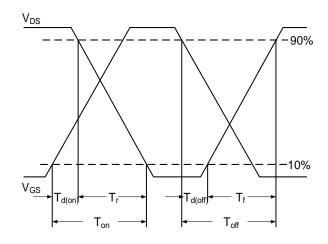


Fig.10 Switching Time Waveform

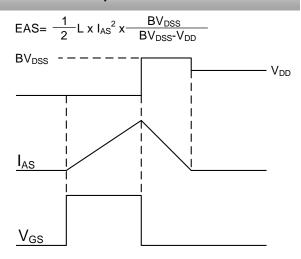


Fig.11 Unclamped Inductive Switching Waveform



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